Microchip Technology - DSPIC33EP128GS805-E/PT Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 17x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gs805-e-pt

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4.6 Instruction Addressing Modes

The addressing modes shown in Table 4-17 form the basis of the addressing modes optimized to support the specific features of individual instructions. The addressing modes provided in the MAC class of instructions differ from those in the other instruction types.

4.6.1 FILE REGISTER INSTRUCTIONS

Most file register instructions use a 13-bit address field (f) to directly address data present in the first 8192 bytes of data memory (Near Data Space). Most file register instructions employ a Working register, W0, which is denoted as WREG in these instructions. The destination is typically either the same file register or WREG (with the exception of the MUL instruction), which writes the result to a register or register pair. The MOV instruction allows additional flexibility and can access the entire Data Space.

4.6.2 MCU INSTRUCTIONS

The three-operand MCU instructions are of the form:

`Operand 3 = Operand 1 <function> Operand 2`

where Operand 1 is always a Working register (that is, the addressing mode can only be Register Direct), which is referred to as Wb. Operand 2 can be a W register fetched from data memory or a 5-bit literal. The result location can either be a W register or a data memory location. The following addressing modes are supported by MCU instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- 5-Bit or 10-Bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions can support different subsets of these addressing modes.

TABLE 4-17: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn form the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn form the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

FIGURE 4-11: BIT-REVERSED ADDRESSING EXAMPLE

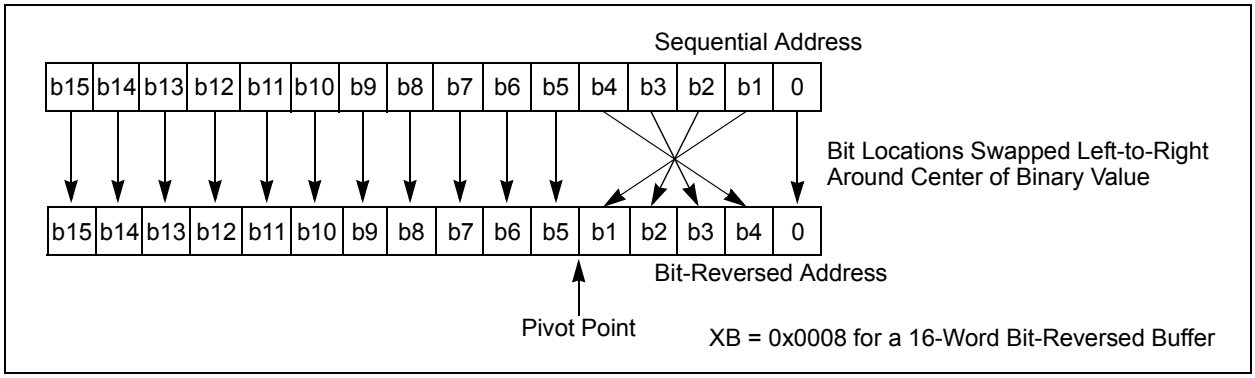


TABLE 4-18: BIT-REVERSED ADDRESSING SEQUENCE (16-ENTRY)

Normal Address					Bit-Reversed Address				
A3	**A2**	**A1**	**A0**	**Decimal**	**A3**	**A2**	**A1**	**A0**	**Decimal**
0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1	0	0	0	8
0	0	1	0	2	0	1	0	0	4
0	0	1	1	3	1	1	0	0	12
0	1	0	0	4	0	0	1	0	2
0	1	0	1	5	1	0	1	0	10
0	1	1	0	6	0	1	1	0	6
0	1	1	1	7	1	1	1	0	14
1	0	0	0	8	0	0	0	1	1
1	0	0	1	9	1	0	0	1	9
1	0	1	0	10	0	1	0	1	5
1	0	1	1	11	1	1	0	1	13
1	1	0	0	12	0	0	1	1	3
1	1	0	1	13	1	0	1	1	11
1	1	1	0	14	0	1	1	1	7
1	1	1	1	15	1	1	1	1	15

TABLE 7-1: INTERRUPT VECTOR DETAILS (CONTINUED)

Interrupt Source	Vector #	IRQ #	IVT Address	Interrupt Bit Location		
				Flag	Enable	Priority
PSES – PWM Secondary Special Event Match	81	73	0x0000A6	IFS4<9> PSESIF	IEC4<9> PSESIE	IPC18<6:4> PSESIP<2:0>
Reserved	82-97	74-89	0x0000A8-0x0000C6	—	—	—
SPI3TX – SPI3 Transfer Done	98	90	0x0000C8	IFS5<10> SPI3TXIF	IEC5<10> SPI3TXIE	IPC22<10:8> SPI3TXIP<2:0>
SPI3RX – SPI3 Receive Done	99	91	0x0000CA	IFS5<10> SPI3RXIF	IEC5<11> SPI3RXIE	IPC22<14:12> SPI3RXIP<2:0>
Reserved	100-101	92-93	0x0000CC-0x0000CE	—	—	—
PWM1 – PWM1 Interrupt	102	94	0x0000D0	IFS5<14> PWM1IF	IEC5<14> PWM1IE	IPC23<10:8> PWM1IP<2:0>
PWM2 – PWM2 Interrupt	103	95	0x0000D2	IFS5<15> PWM2IF	IEC5<15> PWM2IE	IPC23<14:12> PWM2IP<2:0>
PWM3 – PWM3 Interrupt	104	96	0x0000D4	IFS6<0> PWM3IF	IEC6<0> PWM3IE	IPC24<2:0> PWM3IP<2:0>
PWM4 – PWM4 Interrupt	105	97	0x0000D6	IFS6<1> PWM4IF	IEC6<1> PWM4IE	IPC24<6:4> PWM4IP<2:0>
PWM5 – PWM5 Interrupt	106	98	0x0000D8	IFS6<2> PWM5IF	IEC6<2> PWM5IE	IPC24<10:8> PWM5IP<2:0>
PWM6 – PWM6 Interrupt	107	99	0x0000DA	IFS6<3> PWM6IF	IEC6<3> PWM6IE	IPC24<14:12> PWM6IP<2:0>
PWM7 – PWM7 Interrupt	108	100	0x0000DC	IFS6<4> PWM7IF	IEC6<4> PWM7IE	IPC25<2:0> PWM7IP<2:0>
PWM8 – PWM8 Interrupt	109	101	0x0000DE	IFS6<5> PWM8IF	IEC6<5> PWM8IE	IPC25<6:4> PWM8IP<2:0>
Reserved	110	102	0x0000E0	—	—	—
AC2 – Analog Comparator 2 Interrupt	111	103	0x0000E2	IFS6<7> AC2IF	IEC6<7> AC2IE	IPC25<14:12> AC2IP<2:0>
AC3 – Analog Comparator 3 Interrupt	112	104	0x0000E4	IFS6<8> AC3IF	IEC6<8> AC3IE	IPC26<2:0> AC3IP<2:0>
AC4 – Analog Comparator 4 Interrupt	113	105	0x0000E6	IFS6<9> AC4IF	IEC6<9> AC4IE	IPC26<6:4> AC4IP<2:0>
Reserved	114-117	106-109	0x0000E8-0x0000EE	—	—	—
AN0 Conversion Done	118	110	0x0000F0	IFS6<14> AN0IF	IEC6<14> AN0IE	IPC27<10:8> AN0IP<2:0>
AN1 Conversion Done	119	111	0x0000F2	IFS6<15> AN1IF	IEC6<15> AN1IE	IPC27<14:12> AN1IP<2:0>
AN2 Conversion Done	120	112	0x0000F4	IFS7<0> AN2IF	IEC7<0> AN2IE	IPC28<2:0> AN2IP<2:0>
AN3 Conversion Done	121	113	0x0000F6	IFS7<1> AN3IF	IEC7<1> AN3IE	IPC28<6:4> AN3IP<2:0>
AN4 Conversion Done	122	114	0x0000F8	IFS7<2> AN4IF	IEC7<2> AN4IE	IPC28<10:8> AN4IP<2:0>
AN5 Conversion Done	123	115	0x0000FA	IFS7<3> AN5IF	IEC7<3> AN5IE	IPC28<14:12> AN5IP<2:0>
AN6 Conversion Done	124	116	0x0000FC	IFS7<4> AN6IF	IEC7<4> AN6IE	IPC29<2:0> AN6IP<2:0>
AN7 Conversion Done	125	117	0x0000FE	IFS7<5> AN7IF	IEC7<5> AN7IE	IPC29<6:4> AN7IP<2:0>
Reserved	126-131	118-123	0x000100-0x00010A	—	—	—

REGISTER 7-2: CORCON: CORE CONTROL REGISTER(1)

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0
VAR	—	US1	US0	EDT	DL2	DL1	DL0
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	IPL3(2)	SFA	RND	IF
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’= Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **VAR:** Variable Exception Processing Latency Control bit
1 = Variable exception processing is enabled
0 = Fixed exception processing is enabled

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(2)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

Note 1: For complete register details, see Register 3-2.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

10.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, this cannot be practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU Idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

10.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have any effect and read values are invalid.

A peripheral module is enabled only if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note:	If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

10.5 Power-Saving Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page contains the latest updates and additional information.

10.5.1 KEY RESOURCES

- **"Watchdog Timer and Power-Saving Modes"** (DS70615) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 15-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits

- 111 = Center-Aligned PWM mode: Output is set high when OCxTMR = OCxR and set low when OCxTMR = OCxRS(1)
- 110 = Edge-Aligned PWM mode: Output is set high when OCxTMR = 0 and set low when OCxTMR = OCxR(1)
- 101 = Double Compare Continuous Pulse mode: Initializes OCx pin low, toggles OCx state continuously on alternate matches of OCxR and OCxRS
- 100 = Double Compare Single-Shot mode: Initializes OCx pin low, toggles OCx state on matches of OCxR and OCxRS for one cycle
- 011 = Single Compare mode: Compare event with OCxR, continuously toggles OCx pin
- 010 = Single Compare Single-Shot mode: Initializes OCx pin high, compare event with OCxR, forces OCx pin low
- 001 = Single Compare Single-Shot mode: Initializes OCx pin low, compare event with OCxR, forces OCx pin high
- 000 = Output compare channel is disabled

Note 1: OCxR and OCxRS are double-buffered in PWM mode only.

REGISTER 16-20: IOCONx: PWMx I/O CONTROL REGISTER (x = 1 to 8)

R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PENH	PENL	POLH	POLL	PMOD1(1)	PMOD0(1)	OVRENH	OVRENL
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OVRDAT1	OVRDAT0	FLTDAT1(2)	FLTDAT0(2)	CLDAT1(2)	CLDAT0(2)	SWAP	OSYNC
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PENH:** PWMxH Output Pin Ownership bit
1 = PWMx module controls the PWMxH pin
0 = GPIO module controls the PWMxH pin

bit 14 **PENL:** PWMxL Output Pin Ownership bit
1 = PWMx module controls the PWMxL pin
0 = GPIO module controls the PWMxL pin

bit 13 **POLH:** PWMxH Output Pin Polarity bit
1 = PWMxH pin is active-low
0 = PWMxH pin is active-high

bit 12 **POLL:** PWMxL Output Pin Polarity bit
1 = PWMxL pin is active-low
0 = PWMxL pin is active-high

bit 11-10 **PMOD<1:0>:** PWMx I/O Pin Mode bits(1)
11 = PWMx I/O pin pair is in the True Independent Output mode
10 = PWMx I/O pin pair is in the Push-Pull Output mode
01 = PWMx I/O pin pair is in the Redundant Output mode
00 = PWMx I/O pin pair is in the Complementary Output mode

bit 9 **OVRENH:** Override Enable for PWMxH Pin bit
1 = OVRDAT1 provides data for output on the PWMxH pin
0 = PWMx generator provides data for the PWMxH pin

bit 8 **OVRENL:** Override Enable for PWMxL Pin bit
1 = OVRDAT0 provides data for output on the PWMxL pin
0 = PWMx generator provides data for the PWMxL pin

bit 7-6 **OVRDAT<1:0>:** Data for PWMxH, PWMxL Pins if Override is Enabled bits
If OVRENH = 1, OVRDAT1 provides data for the PWMxH pin
If OVRENL = 1, OVRDAT0 provides data for the PWMxL pin

bit 5-4 **FLTDAT<1:0>:** State for PWMxH and PWMxL Pins if FLTMOD<1:0> are Enabled bits(2)
IFLTMOD (FCLCONx<15>) = 0: Normal Fault mode:
If Fault is active, then FLTDAT1 provides the state for the PWMxH pin.
If Fault is active, then FLTDAT0 provides the state for the PWMxL pin.
IFLTMOD (FCLCONx<15>) = 1: Independent Fault mode:
If current limit is active, then FLTDAT1 provides the state for the PWMxH pin.
If Fault is active, then FLTDAT0 provides the state for the PWMxL pin.

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = 1).
2: State represents the active/inactive state of the PWMx depending on the POLH and POLL bits settings.

REGISTER 18-7: SPIxIMSKH: SPIx INTERRUPT MASK REGISTER HIGH

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
RXWIEN	—	RXMSK5(1)	RXMSK4(1,4)	RXMSK3(1,3)	RXMSK2(1,2)	RXMSK1(1)	RXMSK0(1)
bit 15							bit 8

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TXWIEN	—	TXMSK5(1)	TXMSK4(1,4)	TXMSK3(1,3)	TXMSK2(1,2)	TXMSK1(1)	TXMSK0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **RXWIEN:** Receive Watermark Interrupt Enable bit
1 = Triggers receive buffer element watermark interrupt when RXMSK<5:0> ≤ RXELM<5:0>
0 = Disables receive buffer element watermark interrupt

bit 14 **Unimplemented:** Read as '0'

bit 13-8 **RXMSK<5:0>:** RX Buffer Mask bits(1,2,3,4)
RX mask bits; used in conjunction with the RXWIEN bit.

bit 7 **TXWIEN:** Transmit Watermark Interrupt Enable bit
1 = Triggers transmit buffer element watermark interrupt when TXMSK<5:0> = TXELM<5:0>
0 = Disables transmit buffer element watermark interrupt

bit 6 **Unimplemented:** Read as '0'

bit 5-0 **TXMSK<5:0>:** TX Buffer Mask bits(1,2,3,4)
TX mask bits; used in conjunction with the TXWIEN bit.

Note 1: Mask values higher than FIFODEPTH are not valid. The module will not trigger a match for any value in this case.
2: RXMSK2 and TXMSK2 bits are only present when FIFODEPTH = 8 or higher.
3: RXMSK3 and TXMSK3 bits are only present when FIFODEPTH = 16 or higher.
4: RXMSK4 and TXMSK4 bits are only present when FIFODEPTH = 32.

19.0 INTER-INTEGRATED CIRCUIT (I^2C)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGS70X/80X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Inter-Integrated Circuit (I^2C)"** (DS70000195) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGS70X/80X family of devices contains two Inter-Integrated Circuit (I^2C) modules: I2C1 and I2C2.

The I^2C module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard, with a 16-bit interface.

The I^2C module has a 2-pin interface:

- The SCLx/ASCLx pin is clock
- The SDAx/ASDAx pin is data

The I^2C module offers the following key features:

- I^2C Interface supporting both Master and Slave modes of Operation
- I^2C Slave mode Supports 7 and 10-Bit Addressing
- I^2C Master mode Supports 7 and 10-Bit Addressing
- I^2C Port allows Bidirectional Transfers between Master and Slaves
- Serial Clock Synchronization for I^2C Port can be used as a Handshake Mechanism to Suspend and Resume Serial Transfer (SCLREL control)
- I^2C Supports Multi-Master Operation, Detects Bus Collision and Arbitrates Accordingly
- System Management Bus (SMBus) Support
- Alternate I^2C Pin Mapping (ASCLx/ASDAx)

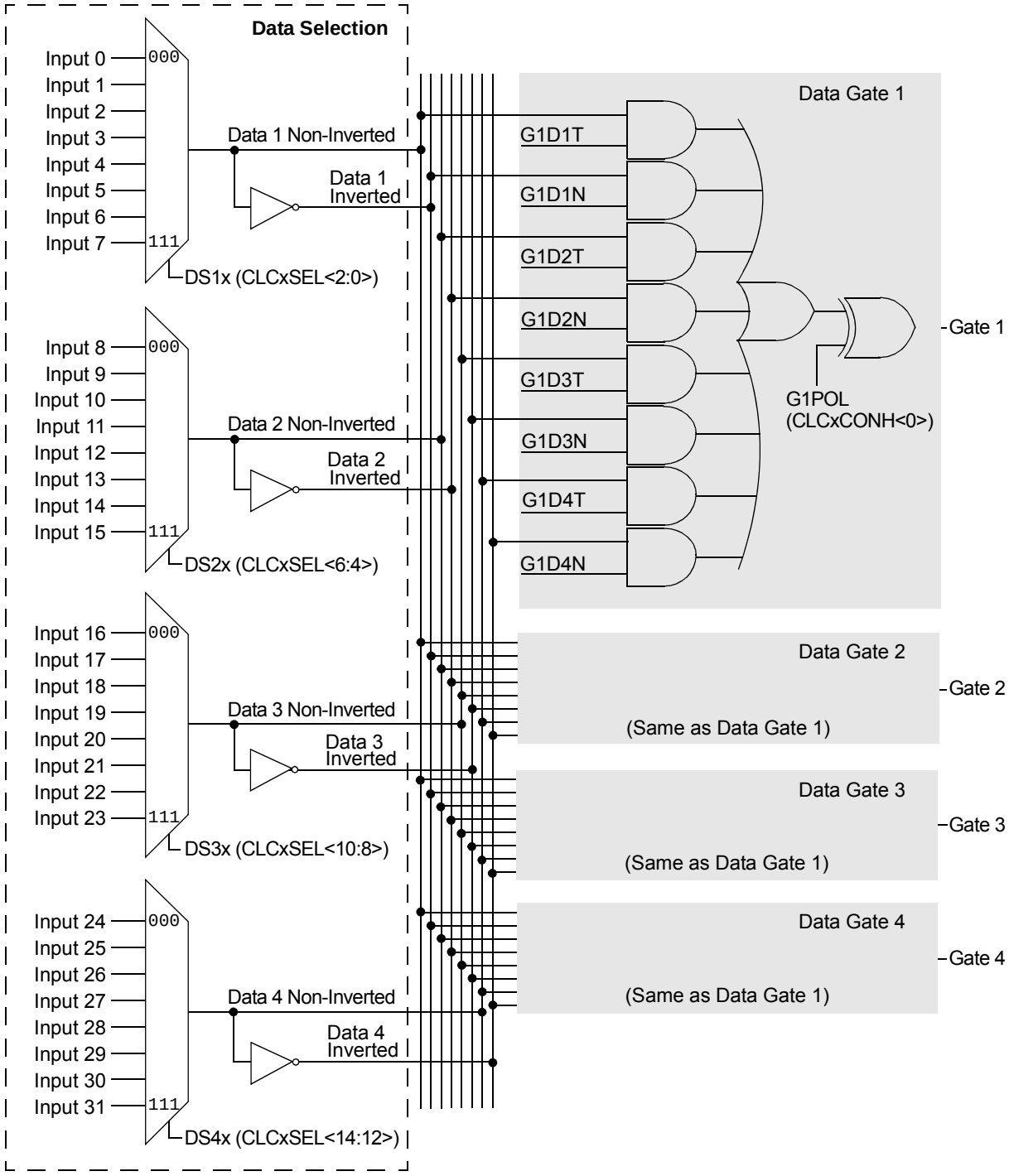
19.1 I^2C Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page contains the latest updates and additional information.

19.1.1 KEY RESOURCES

- **"Inter-Integrated Circuit (I^2C)"** (DS70000195) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 21-3: CLCx INPUT SOURCE SELECTION DIAGRAM



Note: All controls are undefined at power-up.

TABLE 21-2: CLC2 MULTIPLEXER INPUT SOURCES

DSx<2:0>		Signal Source
DS1<2:0>	000	CLCINA
	001	System Clock
	010	Timer1 Match
	011	PWM3H
	100	PWM7L
	101	High-Speed PWM Clock
	110	Timer2 Match
	111	Timer3 Match
DS2<2:0>	000	CLCINB
	001	CLC1 Out
	010	CMP1 Out
	011	UART2 TX Out
	100	ADC End-of-Conversion
	101	DMA Channel 0 Interrupt
	110	PWM3L
	111	PWM7H
DS3<2:0>	000	CLCINA
	001	CLC2 Out
	010	CMP2 Out
	011	SPI2 SDO Out
	100	UART2 RX
	101	PWM4H
	110	PWM8L
	111	OCMP2
DS4<2:0>	000	CLCINB
	001	CLC1 Out
	010	CMP3 Out
	011	SDI2
	100	PTG
	101	ECAN1
	110	PWM4L
	111	PWM8H

NOTES:

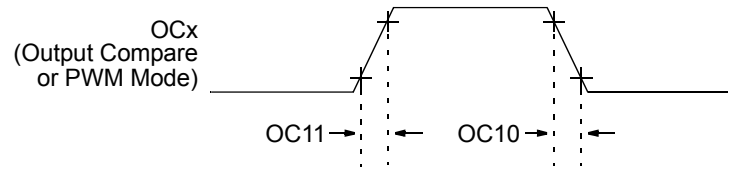
TABLE 30-23: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SY00	TPU	Power-up Period	—	400	600	μs	
SY10	TOST	Oscillator Start-up Time	—	1024 TOSC	—	—	TOSC = OSC1 period
SY12	TWDT	Watchdog Timer Time-out Period	0.81	—	1.22	ms	WDTPRE = 0, WDTPOST<3:0> = 0000, using LPRC tolerances indicated in F21 (see Table 30-21) at +85°C
			3.25	—	4.88	ms	WDTPRE = 1, WDTPOST<3:0> = 0000, using LPRC tolerances indicated in F21 (see Table 30-21) at +85°C
SY13	TIOZ	I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	0.68	0.72	1.2	μs	
SY20	TMCLR	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	
SY30	TBOR	BOR Pulse Width (low)	1	—	—	μs	
SY35	TFSCM	Fail-Safe Clock Monitor Delay	—	500	900	μs	-40°C to +85°C
SY36	TVREG	Voltage Regulator Standby-to-Active mode Transition Time	—	—	30	μs	
SY37	TOSCDFRC	FRC Oscillator Start-up Delay	—	48	—	μs	
SY38	TOSCDLPRC	LPRC Oscillator Start-up Delay	—	—	70	μs	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 3.3V, +25°C unless otherwise stated.

FIGURE 30-7: OUTPUT COMPARE x MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-28: OUTPUT COMPARE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-8: OCx/PWMx MODULE TIMING CHARACTERISTICS

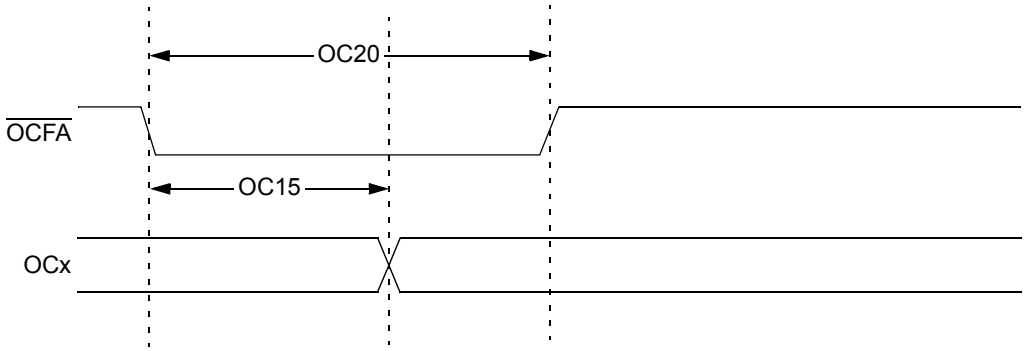


TABLE 30-29: OCx/PWMx MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWMx I/O Change	—	—	TCY + 20	ns	
OC20	TFLT	Fault Input Pulse Width	TCY + 20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-25: SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS(1,2)

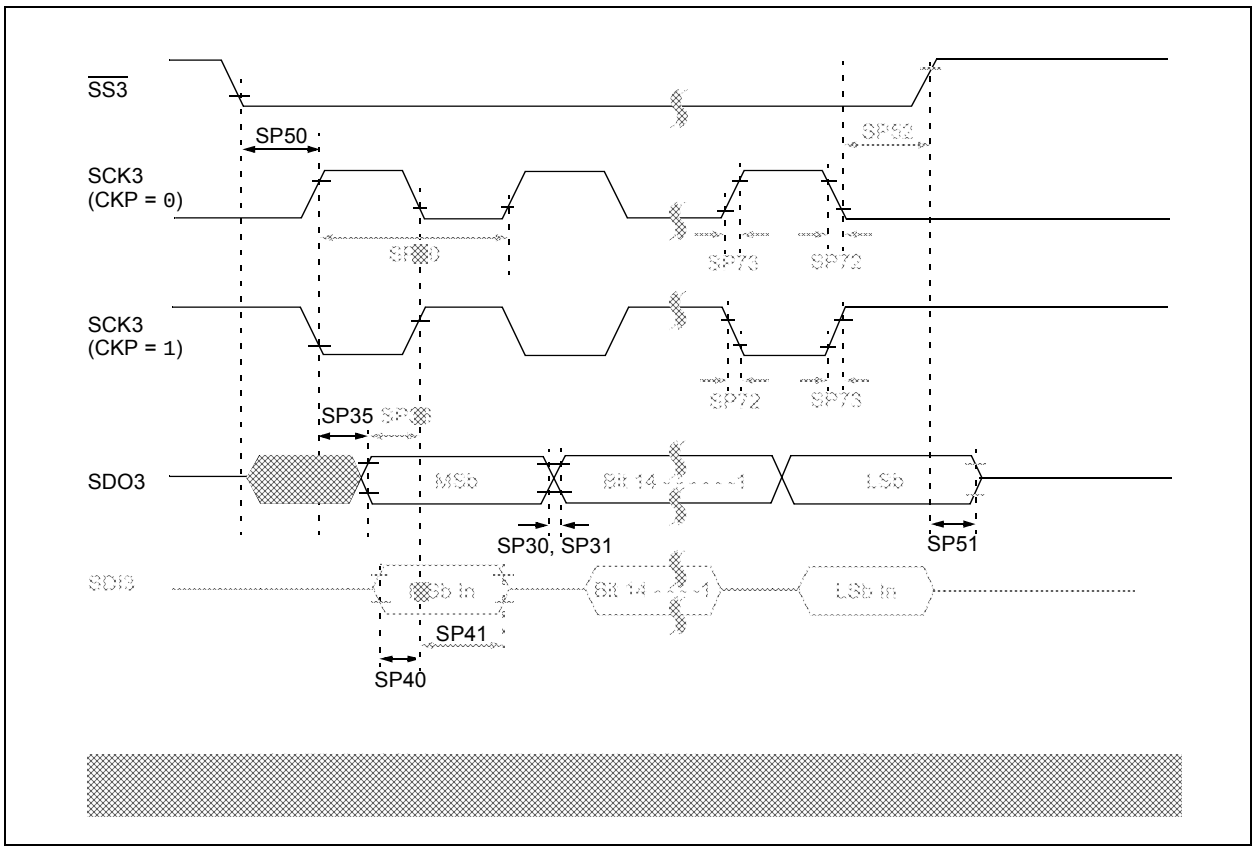


TABLE 30-45: SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS(5)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK3 Input Frequency	—	—	25	MHz	**(Note 3)**
SP72	TscF	SCK3 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK3 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO3 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO3 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO3 Data Output Valid after SCK3 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO3 Data Output Setup to First SCK3 Edge	20	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI3 Data Input to SCK3 Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI3 Data Input to SCK3 Edge	15	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS3}$ ↓ to SCK3 ↑ or SCK3 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS3}$ ↑ to SDO3 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SS3}$ ↑ after SCK3 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK3 is 66.7 ns. Therefore, the SCK3 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI3 pins.

5: For dsPIC33EPXXXGSX06 and dsPIC33EPXXXGSX08 devices with a fixed SCK3 pin.

TABLE 30-52: ADC MODULE SPECIFICATIONS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)[5] Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
ADC Accuracy: Single-Ended Input							
AD20b	Nr	Resolution	12			bits	
AD21b	INL	Integral Nonlinearity	> 5	—	< 5	LSb	AVSS = 0V, AVDD = 3.3V
AD22b	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	AVSS = 0V, AVDD = 3.3V **(Note 2)**
AD23b	GERR	Gain Error (Dedicated Core)	> 0	8	< 15	LSb	AVSS = 0V, AVDD = 3.3V
		Gain Error (Shared Core)	> 5	15	< 22	LSb	
AD24b	EOFF	Offset Error (Dedicated Core)	> 2	9	< 15	LSb	AVSS = 0V, AVDD = 3.3V
		Offset Error (Shared Core)	> 5	17	< 22	LSb	
AD25b	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance							
AD31b	SINAD	Signal-to-Noise and Distortion	63	—	> 65	dB	**(Notes 3, 4)**
AD34b	ENOB	Effective Number of Bits	10.3	—	—	bits	**(Notes 3, 4)**

Note 1: These parameters are not characterized or tested in manufacturing.

2: No missing codes, limits based on characterization results.

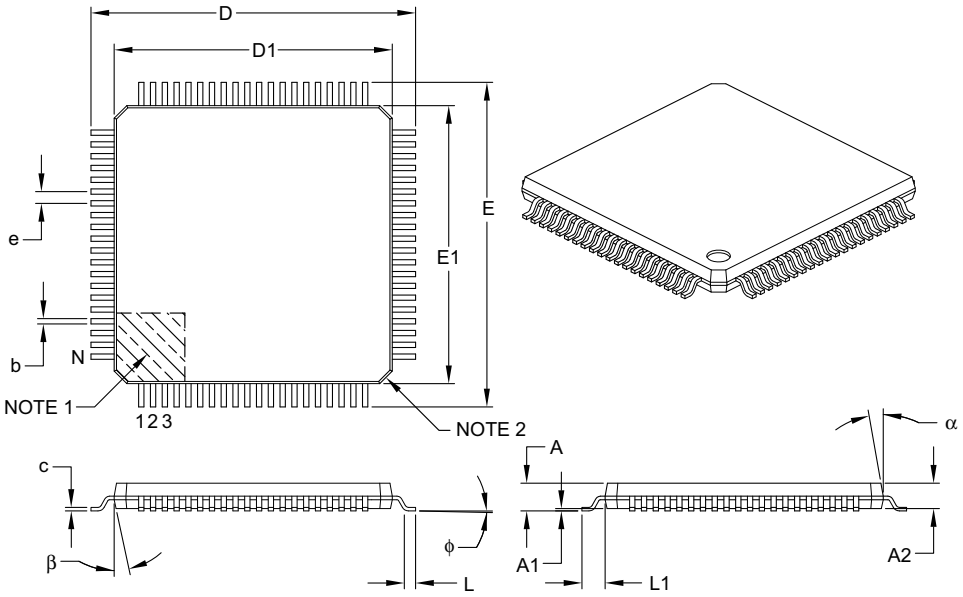
3: These parameters are characterized but not tested in manufacturing.

4: Characterized with a 15 kHz sine wave.

5: The ADC module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is ensured, but not characterized.

80-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		80	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		14.00 BSC	
Overall Length	D		14.00 BSC	
Molded Package Width	E1		12.00 BSC	
Molded Package Length	D1		12.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-092B

NOTES: